

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

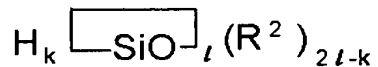
1.(Currently Amended) Organic siloxane resins, which are condensed polymers, manufactured by a hydrolysis and condensation reaction of silane compounds comprising one or more kinds of hydrosilane compounds ~~under~~ in the presence of a base catalyst, wherein the hydrosilane compounds have the following Chemical Formula 1, or are oligomers manufactured from the silane compounds in the Chemical Formula 1 or cyclic siloxane compounds having the following Chemical Formula 2, and the weight average molecular weight of the resins is at least 5,000;

[Chemical Formula 1]



wherein R¹ is independently fluorine, aryl, vinyl, allyl, or linear or branched alkyl having 1 to 4 carbon atoms substituted or unsubstituted with fluorine, or alkoxy; and n is an integer of 1 to 3; and

[Chemical Formula 2]



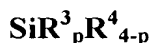
wherein R² is independently fluorine, aryl, vinyl, allyl, or linear or branched alkyl having 1 to 4 carbon atoms substituted or unsubstituted with fluorine, or alkoxy; and k and l are integers of 3 to 10.

2. (Original) The organic siloxane resins according to Claim 1, wherein said silane compounds are comprised of hydrosilane compounds entirely, or of hydrosilane compounds and organic silane compounds other than said hydrosilane compounds.

3. (Canceled)

4. (Currently Amended) The organic silane resins according to Claim 2, wherein said organic silane compounds other than said hydrosilane compounds are silane compounds having a chemical formula represented by the following Chemical Formula 3 or 4:

[Chemical Formula 3]



where R^3 is independently fluorine, aryl, vinyl, allyl, or linear or branched [[C1~4]] alkyl having 1 to 4 carbon atoms substituted or unsubstituted with fluorine; R^4 is independently acetoxy, hydroxy, or linear or branched [[C1~4]] alkoxy having 1 to 4 carbon atoms; and p is an integer of 0 to 3; and

[Chemical Formula 4]



where R^5 and R^7 are independently fluorine, aryl, vinyl, allyl, or linear or branched [[C1~4]] alkyl having 1 to 4 carbon atoms substituted or unsubstituted with fluorine; R^6 and R^8 are independently acetoxy, hydroxy, or linear or [[C1~4]] alkoxy having 1 to 4 carbon atoms; M is alkylene or phenylene having 1 to 6 carbon atoms; and q and r are integers of 0 to 3.

5. (Previously Presented) Compositions for forming insulating films comprising said organic siloxane resins manufactured according to Claim 1.

6. (Currently Amended) A method of forming insulating films using organic siloxane resins comprising the steps of:

- a) preparing an organic siloxane resin according to claim 1;
- b) dissolving the organic siloxane resin in an organic solvent to prepare a solution;

- c) forming an insulating film by coating ~~[[a]] the solution, which is prepared by dissolving the above organic siloxane resin in organic solvent; and~~
- d) drying and hardening the insulating film formed in the above.

7. (Currently Amended) The method of forming a insulating film using said organic siloxane resins according to Claim 6, further comprising a step, after the above step b), of adding one or more kinds of additives selected from the group consisting of organic molecules, ~~organic polymers, organic dendrimers,~~ water, pH controlling agents, colloidal silica, and surfactants to said solution.

8. (Previously Presented) Insulation films using organic siloxane resins manufactured by drying and hardening insulating films formed by coating the solution, which is prepared by dissolving said organic siloxane resins according to Claim 1 in an organic solvent, onto a substrate.

9. (Currently Amended) Electronic devices comprising insulating films using organic siloxane resins manufactured by drying and hardening of insulating films formed by coating the solution, which is prepared by dissolving said organic siloxane resins according to Claim 1 in an organic solvent, onto a substrate.